Product Data Sheet

PC/104-Plus pin header,
Part No. 272-30000-31

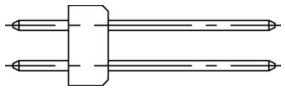




Illustration similar



Parallel



Press-fit

- tail length 2.8 mm
- number of positions: 60
- performance level 3

» to product on www.ept.de

» to product group PC/104, PC/104-Plus

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Product Data Sheet

PC/104-Plus pin header, Part No. 272-30000-31

Technical Specifications

Basics

Specification	PC/104-Plus
Performance Level	3
No. of Contacts	60
Termination Technology	press-fit technology
Termination Length	2.8 mm
Board-to-Board Distance	15.24 mm & 22 mm
Operating Temperature Range	-55°C to +125°C

Material

Insulator Material	glass-fiber reinforced PBT, UL 94 V-0
Contact Material	copper alloy

Mechanical

Pitch	2.0 mm
Mating Force per Pin	max. 1.5 N
Separating Force per Pin	at least 0.3 N
Press-fit force	max. 90 N/pin

Electrical

Operational Current	max. 1.7 A
Operational Voltage	100 V
Contact Resistance	20 mΩ
Clearance and Creepage	at least 0.5 mm
Insulation Resistance	$>10^6$ MΩ

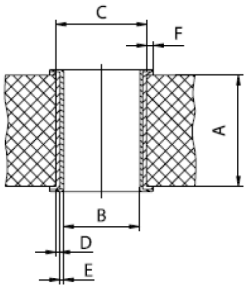
Approval / Compliance

UL file	E130314
Environment	RoHS compliant

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Hole Specifications

Plated through-hole according to IEC 60352-5



Material	chem. Sn Leiterplatten
Nominal Hole	**Ø 0.85 mm**
A PCB Thickness	min. 1.44 mm
B Plated Hole	Ø 0.85 +0.10 / -0.05 mm
C Drill Hole	1.0 ±0.025 mm
D Cu Plating	min. 25 µm
E Surface	chem. Sn Schicht, max. 1.5 µm
F Annular Ring	min. 0.1 mm

Material	Ni, Au Leiterplatten
Nominal Hole	**Ø 0.85 mm**
A PCB Thickness	min. 1.44 mm
B Plated Hole	Ø 0.85 +0.10 / -0.05 mm
C Drill Hole	1.0 ±0.025 mm
D Cu Plating	min. 25 µm
E Surface	Ni, Au Schicht, 0.05 - 0.2 µm Au über 2.5 - 5 µm Ni
F Annular Ring	min. 0.1 mm

Material	rein Cu Leiterplatten
Nominal Hole	**Ø 0.85 mm**
A PCB Thickness	min. 1.44 mm
B Plated Hole	Ø 0.85 +0.10 / -0.05 mm
C Drill Hole	1.0 ±0.025 mm
D Cu Plating	min. 25 µm
E Surface	OSP*, z.B. GLICOAT-SMD (F2) mit 0.12 - 0.15 µm
F Annular Ring	min. 0.1 mm

Material	HAL Sn Leiterplatten
Nominal Hole	**Ø 0.85 mm**
A PCB Thickness	min. 1.44 mm
B Plated Hole	Ø 0.85 +0.10 / -0.05 mm
C Drill Hole	1.0 ±0.025 mm
D Cu Plating	min. 25 µm
E Surface	HAL Sn, 5 - 15 µm
F Annular Ring	min. 0.1 mm

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Drawings

Component data in 2D and 3D format you can download here:

» PDF » 3D IGES » 3D STEP » 3D PDF

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